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Dimensions	
Chip Size	1808
L	4.572mm +/-0.381mm (0.18 in +/-0.015 in)
W	2.032mm +/-0.381mm (0.08 in +/-0.015 in)
T	1.651mm MAX (0.065 in MAX)

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	25000

General Information	
Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Ultra Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	646e40c8-ce81-456e-b9ed-50112f3d27a5
Termination	Nickel
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	560 pF
Capacitance Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

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